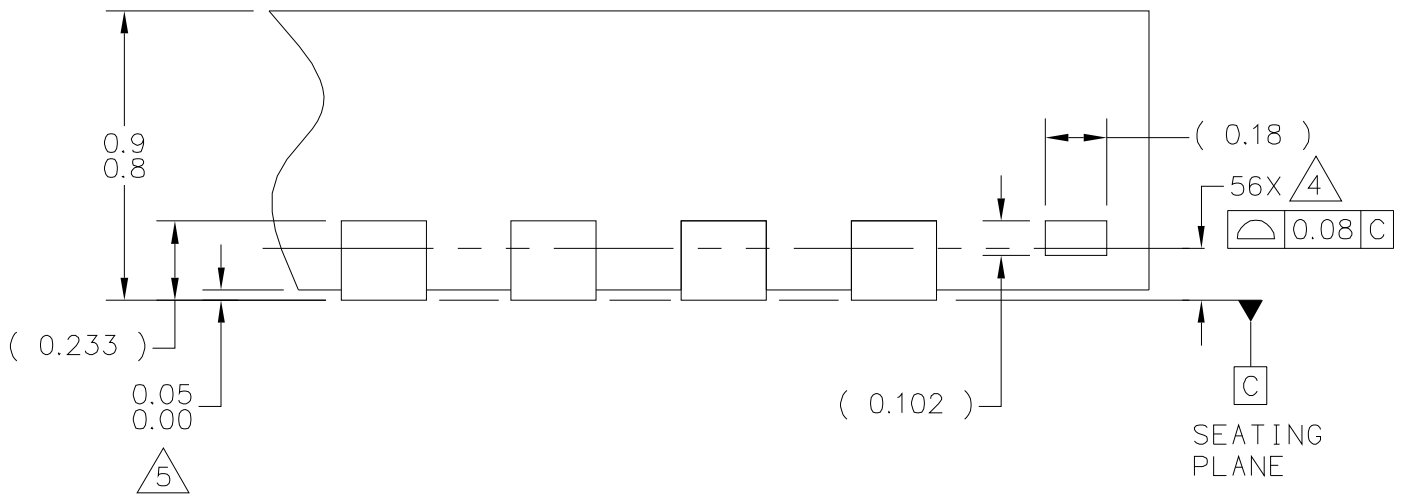


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TITLE: QFN, THERMALLY ENHANCED 8 X 8 X 0.85, 0.5 PITCH, 56 I/O	DOCUMENT NO: 98ASA00405D	REV: 0	
	CASE NUMBER: 2241-01	22 DEC 2011	
	STANDARD: NON-JEDEC		



DETAIL E  
VIEW ROTATED 90° CW

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**MECHANICAL OUTLINE**

PRINT VERSION NOT TO SCALE

TITLE:  
QFN, THERMALLY ENHANCED  
8 X 8 X 0.85, 0.5 PITCH, 56 I/O

DOCUMENT NO: 98ASA00405D

REV: 0

CASE NUMBER: 2241-01

22 DEC 2011

STANDARD: NON-JEDEC

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING & TOLERANCING PER ASME Y14.5 – 1994.

△3. THIS DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL TIP.

△4. BILATERAL COPLANARITY ZONE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

△5. THIS DIMENSION APPLIES ONLY FOR TERMINALS.

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